ABSTRACT

A method of making semiconductor devices comprising the steps of: preparing non-defective individual insulating films (12) having good quality, wherein leads (20) are formed and a semiconductor chip (16) is mounted on each of the leads (20); attaching each of the non-defective individual insulating films (12) to each of mounting portions (46) of a plate (40); and cutting the plate (40) into separate pieces, each of the separated pieces corresponding to each of the mounting portions (46) on which each of the non-defective individual insulating films (12) is mounted.